


**THERMAL RESISTANCE RATINGS**

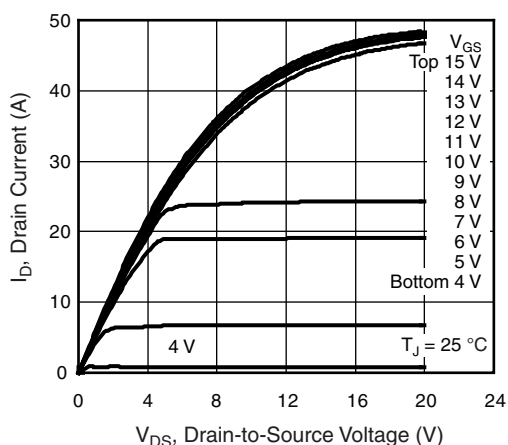
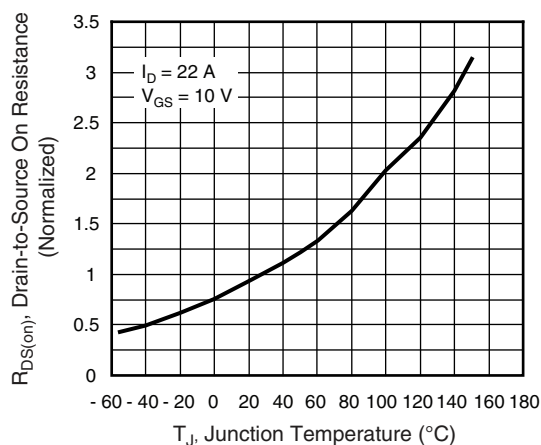
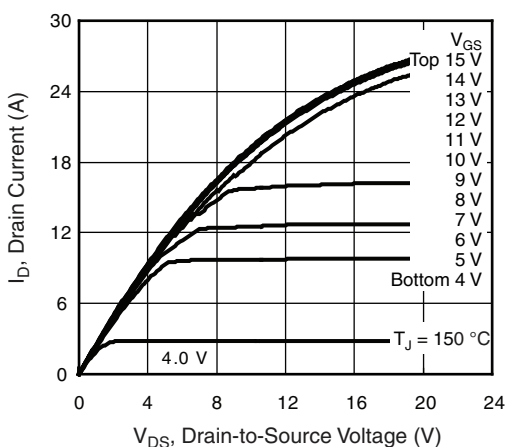
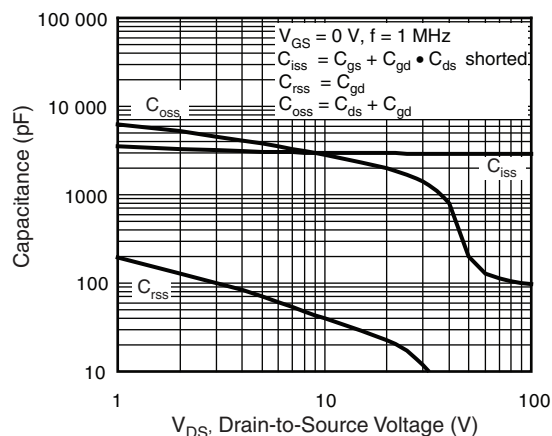
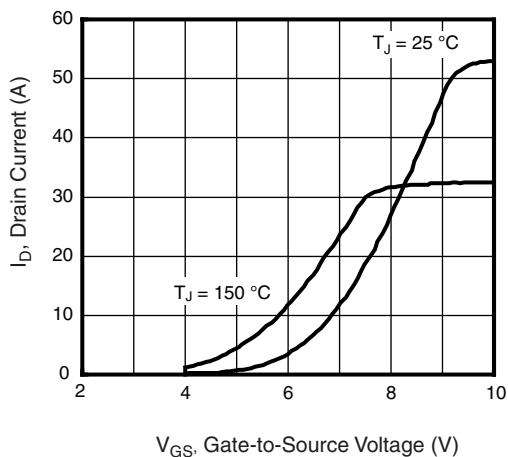
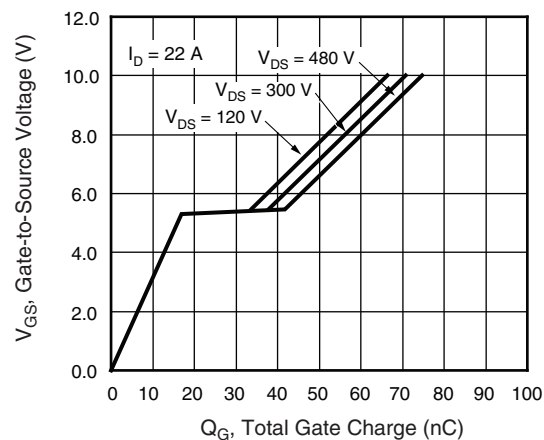
PARAMETER		SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	TO-220AB	$R_{thJA}$	-	62	°C/W
Maximum Junction-to-Case (Drain)	TO-220AB	$R_{thJC}$	-	0.5	

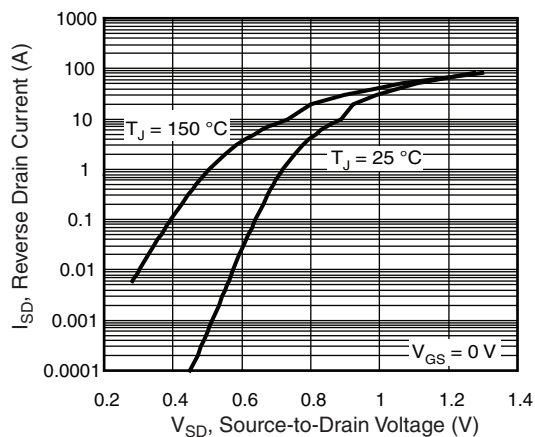
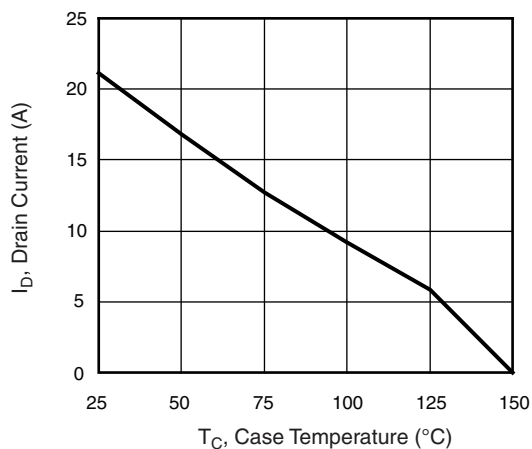
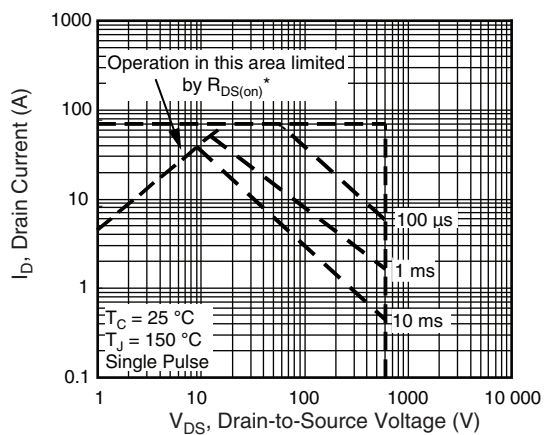
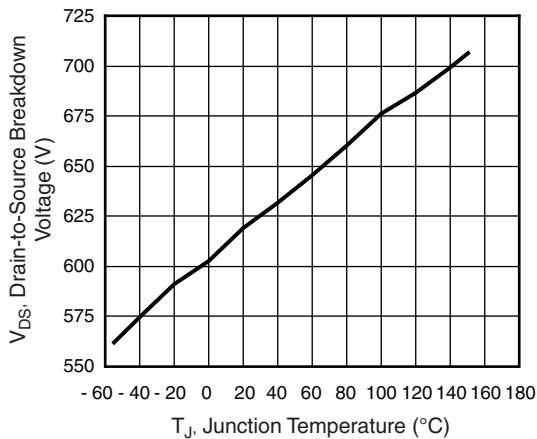
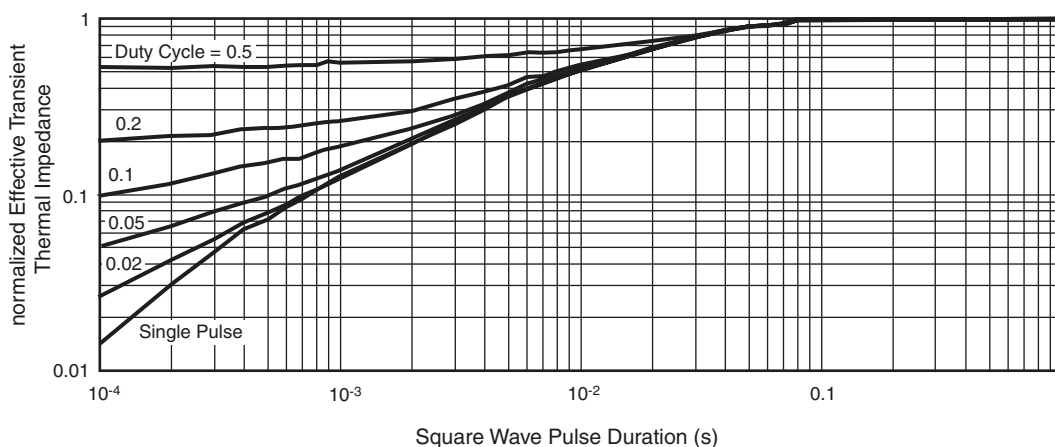
**SPECIFICATIONS** ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

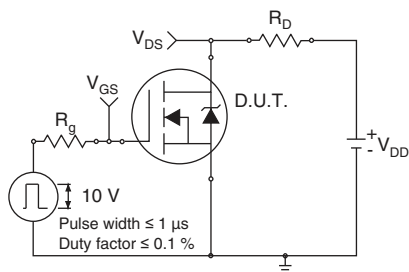
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA		600	-	-	V
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.70	-	V/°C
Gate-Source Threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		2.0	-	4.0	V
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
		V <sub>GS</sub> = ± 30 V		-	-	± 1	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V		-	-	1	μA
		V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C		-	-	100	
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.160	0.190	Ω
Forward Transconductance <sup>a</sup>	g <sub>fs</sub>	V <sub>DS</sub> = 50 V, I <sub>D</sub> = 13 A		-	9.4	-	S
Dynamic							
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 25 V, f = 1.0 MHz		562	2810	5620	pF
Output Capacitance	C <sub>oss</sub>			296	1480	2960	
Reverse Transfer Capacitance	C <sub>rss</sub>			6.6	33	66	
Effective Output Capacitance (Time Related)	C <sub>oss eff.</sub> (TR) <sup>a</sup>	V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 0 V to 480 V	-	155	-	nC
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 22 A, V <sub>DS</sub> = 480 V	-	75	110	
Gate-Source Charge	Q <sub>gs</sub>			-	17	-	
Gate-Drain Charge	Q <sub>gd</sub>			-	25	-	
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 380 V, I <sub>D</sub> = 22 A, R <sub>g</sub> = 9.1 Ω, V <sub>GS</sub> = 10 V		-	24	50	ns
Rise Time	t <sub>r</sub>			-	68	100	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	77	115	
Fall Time	t <sub>f</sub>			-	59	90	
Gate Input Resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.13	0.65	1.3	Ω
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	22	A
Pulsed Diode Forward Current	I <sub>SM</sub>			-	-	88	
Diode Forward Voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C, I <sub>S</sub> = 22 A, V <sub>GS</sub> = 0 V		-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25 °C, I <sub>F</sub> = I <sub>S</sub> , dI/dt = 100 A/μs, V <sub>R</sub> = 25 V		-	462	690	ns
Reverse Recovery Charge	Q <sub>rr</sub>			-	8.3	16	μC
Reverse Recovery Current	I <sub>RRM</sub>			-	30	60	A

**Note**

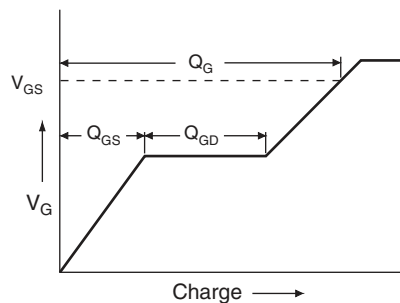
a.  $C_{oss\text{ eff. (TR)}}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ .

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Fig. 1 - Typical Output Characteristics,  $T_J = 25^\circ\text{C}$** 

**Fig. 4 - Normalized On-Resistance vs. Temperature**

**Fig. 2 - Typical Output Characteristics,  $T_J = 150^\circ\text{C}$** 

**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**

**Fig. 3 - Typical Transfer Characteristics**

**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**

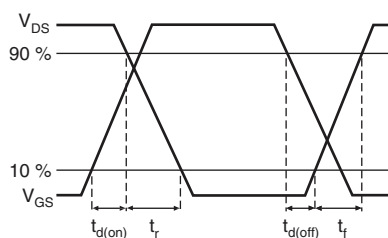

**Fig. 7 - Typical Source-Drain Diode Forward Voltage**

**Fig. 9 - Maximum Drain Current vs. Case Temperature**

**Fig. 8 - Maximum Safe Operating Area**

**Fig. 10 - Drain-to-Source Breakdown Voltage**

**Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case**



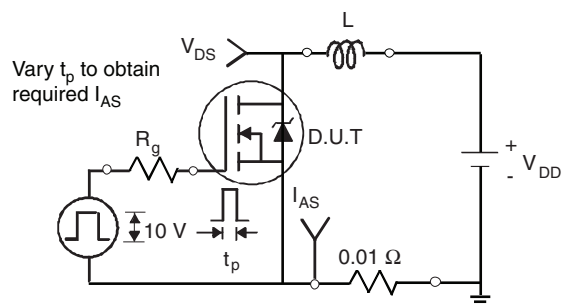
**Fig. 12 - Switching Time Test Circuit**



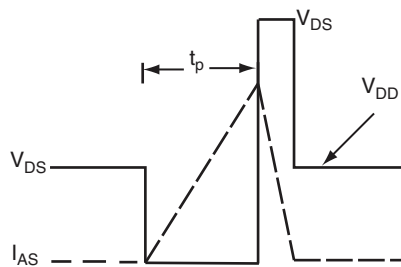
**Fig. 16 - Basic Gate Charge Waveform**



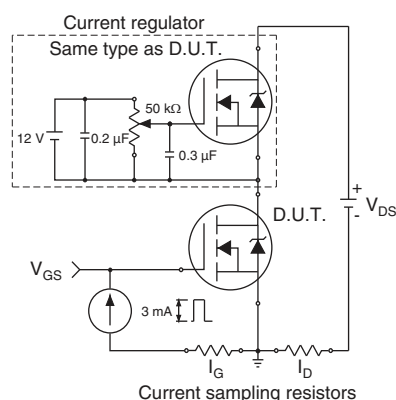
**Fig. 13 - Switching Time Waveforms**



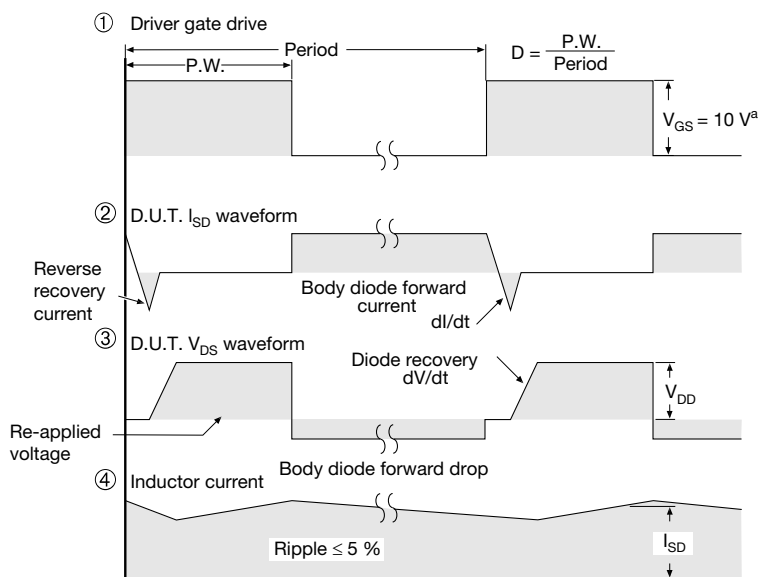
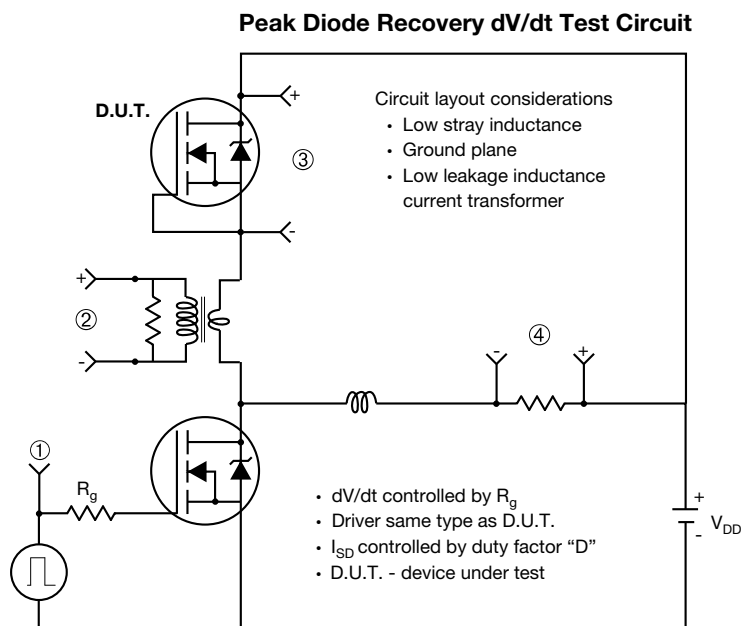
**Fig. 14 - Unclamped Inductive Test Circuit**



**Fig. 15 - Unclamped Inductive Waveforms**



**Fig. 17 - Gate Charge Test Circuit**


**Note**

a.  $V_{GS} = 5 V$  for logic level devices

**Fig. 18 - For N-Channel**

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